IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005, IPC, B	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Infor	mation														
Company name*			Company unique ID			Unique ID Authority					Response Date*				
nsemi											2023-06-08				
Contact Name		Title - C	Title - Contact			Phone - Contact*				Email	Email - Contact*				
Product-Env-Stev	wards	Product	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
uthorized Repres	sentative*	Title - R	Title - Representative			Phone - Representative*				Email	Email - Representative*				
Product-Env-Stev	wards	Product	Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	Mfr Item Number	em Number Mfr Item Name			Effective Date	Version	rsion Manufacturing Site		ite	Weight* UOM		UOM	Unit Type	
	1	NB7VPQ16MMN	EQU/PREEMP SINGLE CHANNEL			2023-06-08	MY1			23.06 mg		mg	Each		
	g Proccess Information														
Termina	al Plating / Grid Array Material	Terminal B	Terminal Base Alloy		-020 MSL Rating		Peak Process Body Temperature		Max Time at	Peak Tempera	ak Temperature Number of Re		Reflow Cyc	eles	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		(no CU Alloy	CU Alloy 1			260		C 30		seco	seconds 3		3		
Comments															
vel 1 - maximum	ı time at peak temperature du	ıring soldering is	10-30 seconds												
or more informat	tion regarding material comp	osition please ref	er to page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.25	mg	Supplier	Silicon (Si)	7440-21-3		0.25	mg
Die Attach	0.65	mg	Supplier	Silver (Ag)	7440-22-4		0.4875	mg
			Supplier	Epoxy resins	129915-35-1		0.1625	mg
Lead Frame	9.38	mg	Supplier	Tin (Sn)	7440-31-5		0.0235	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0206	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0235	mg
			Supplier	Copper (Cu)	7440-50-8		9.3125	mg
Mold Compound-Black	12.09	mg		Epoxy resin	proprietary data		0.5682	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.209	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0121	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		9.7325	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.5682	mg
Plating	0.55	mg	Supplier	Palladium (Pd)	7440-05-3		0.0132	mg
			В	Nickel (Ni)	7440-02-0		0.484	mg
			Supplier	Gold (Au)	7440-57-5		0.0528	mg
Wire Bond - Au	0.14	mg	Supplier	Gold (Au)	7440-57-5		0.14	mg